

N700C

Non-Silicone Thermal Conductive Pad

Non-Silicone Thermal Compound N700C is made of non-silicon resin material. No low-molecular-weight siloxane volatilization, no electrical contact & pollution problems. N700C is flexible and has great thermal conduction, making the thermal resistance as low as possible. The thermal conductivity is 5.0W/m*K. It's suitable for optical and sensitive electric components.

■ FEATURES

- / Thermal conductivity:5.0 W/m*K
- / It's made by non-silicone resin materials
- / Low contact thermal resistance
- / With electrical insulation
- / Outstanding thermal conductivity
- / Applicable to optical and sensitive electric components

■ TYPICAL APPLICATION

- / HDDS
- / Optical appliance

■ SPECIFICATIONS

- / Sheet form
- / Die-cut parts



■ TYPICAL PROPERTIES

PROPERTY	N700C	TEST METHOD	UNIT
Color	Gray	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	3.2	ASTM D792	g/cm ³
Hardness	55	ASTM D2240	Shore OO
Tensile Strength	0.15	ASTM D412	Kgf/cm ²
Application temperature	-60~125	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	16	ASTM D5470 modify	%
Deflection @20 psi	46	ASTM D5470 modify	%
Deflection @30 psi	68	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	8	ASTM D149	KV/mm
Surface resistivity	>10 ¹¹	ASTM D257	Ohm
Volume resistivity	>10 ¹⁰	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	5.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.312	ASTM D5470	°C-in ² / W
Thermal impedance@20 psi	0.208	ASTM D5470	°C-in ² / W
Thermal impedance@30 psi	0.132	ASTM D5470	°C-in ² / W

The chemical formula indicates that if Cyclic polydimethylsilox-ane (HO-[Si(CH₃)₂O]_n-H) is non-reaction, it's volatile anytime and everywhere. For example, when the electric products which has been put in a confined space, the volatile of low-molecular-weight silox-anes will makes the elecetic products uncontacted.

Thermal Resistance vs. Pressure vs. Deflection

